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| U.S. Department of Commerce, Patent and Trademark Office | | | | Atty Docket No. | | Serial No. | | |
| | | | | M-11685 US | | 09/905,474 | | |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | | | | Applicant(s) | | | | |
| (Use several sheets if necessary) | | | | Saputro, Stephanus D.; Zhang, Lan | | | | |
| | | | | Filing Date | | Group | | |
| | | | | July 13, 2001 | | 2827 | | |
| U.S. Patent Documents | | | | | | | | |
| *Examiner Initial | | Document Number | Date | Name | Class | Subclass | Filing Date If Appropriate | |
| | AA | | | | | | | |
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| Foreign Patent Documents | | | | | | | | |
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| | | Document | Date | Country | Class | Subclass | Yes | No |
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| | AM | | | | | | | |
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| OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.) | | | | | | | | |
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| | AR | Doreen S. Fisher and Thad McMillian, "Printed Circuit Assembly Having Conductive Pad Array With In-Line Via Placement", June 28, 2000, Serial No. 09/605,905. 361/777 Au 28472822 | | | | | | |
| | AS | | | | | | | |
| Examiner | | John B. Vignata Date Considered June 29, 2003 | | | | | | |
| *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant. | | | | | | | | |

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